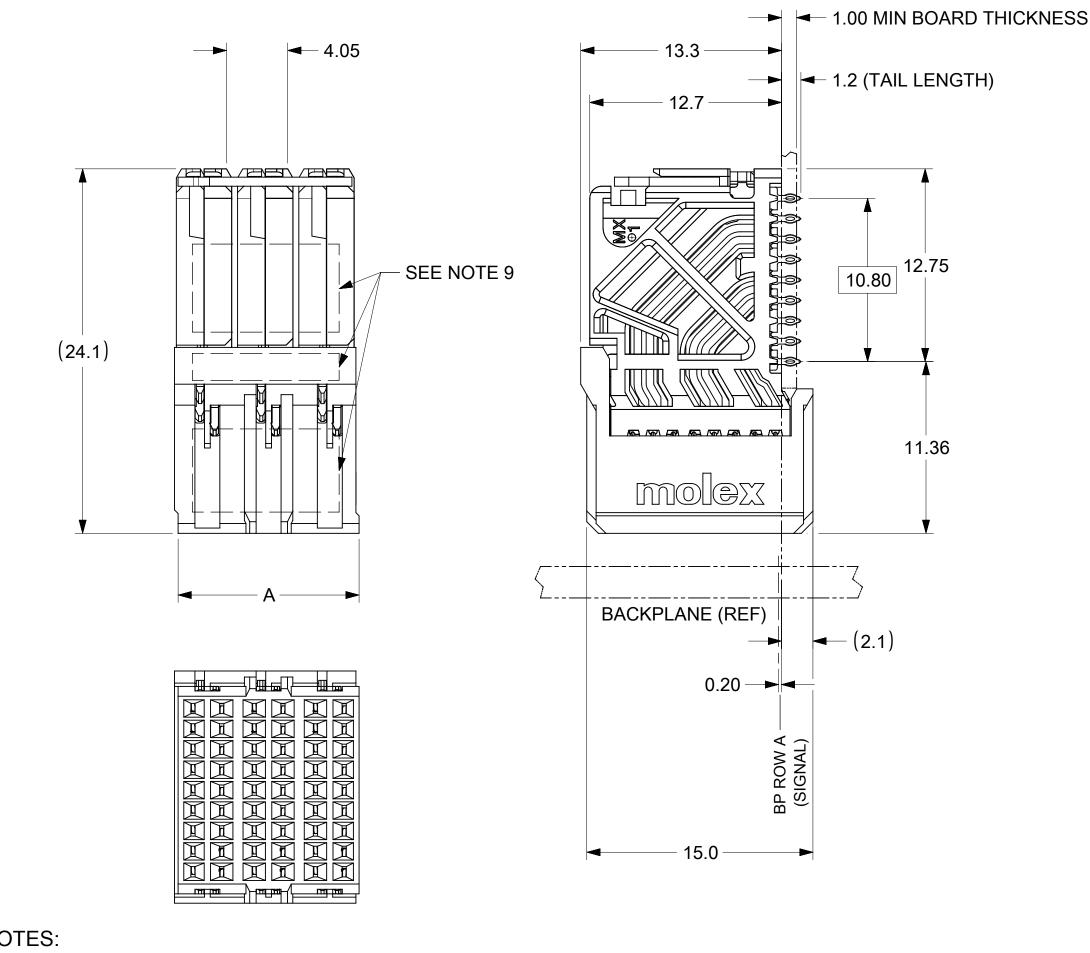
	12	11		10		9		8		
н	MATERIAL NUMBER	# OF COLUMNS	# OF DIFF PAIR		DIM "A" MAX	DIM "B"	PTHØ			
	76860-1006	6		18	12.15	10.00	0.46±0	0.05)5	
	76860-1036	6		18	12.15	10.00	0.39±0	0.05		
	76860-1008	8		24	16.20	14.05	0.46±0	0.05		
	76860-1038	8		24	16.20	14.05	0.39±0	0.05		



6

MODULE & TAIL PLATING TYPE 1 = UNGUIDED, LEAD-FREE

7



NOTES:

G

D

С

B

1. MATERIALS: HOUSING - LIQUID CRYSTAL POLYMER (LCP), GLASS-FILLED, UL94V-0 **TERMINALS - HIGH PERFORMANCE COPPER ALLOY**

- 2. FINISH: 30µIN MIN GOLD IN CONTACT AREA. SELECTIVE TIN ON PCB TAILS. NICKEL OVERALL.
- 3. REFER TO MOLEX PRODUCT SPEC PS-76060-999 FOR PERFORMANCE SPECIFICATIONS AND ADDITIONAL PCB INFORMATION.
- 4. EACH SIGNAL WAFER CONTAINS 2 COLUMNS OF TERMINALS.
- 5. PRODUCT IS PACKAGED PER PK-70873-591.
- 6. THIS PART CONFORMS TO CLASS B REQUIREMENTS OF COSMETIC SPEC PS-45499-002.
- 7. REFER TO MOLEX SALES DRAWING SD-76855-001 FOR THE MATING HEADERS.
- 8. REFER TO MOLEX ROUTING GUIDE AS-76850-990 FOR ADDITIONAL PCB LAYOUT AND ROUTING RECOMMENDATIONS.
- 9. MARKING: LOCATED APPROXIMATELY AS SHOWN. PART NUMBER AND DATE CODE.

